

Fig. 1

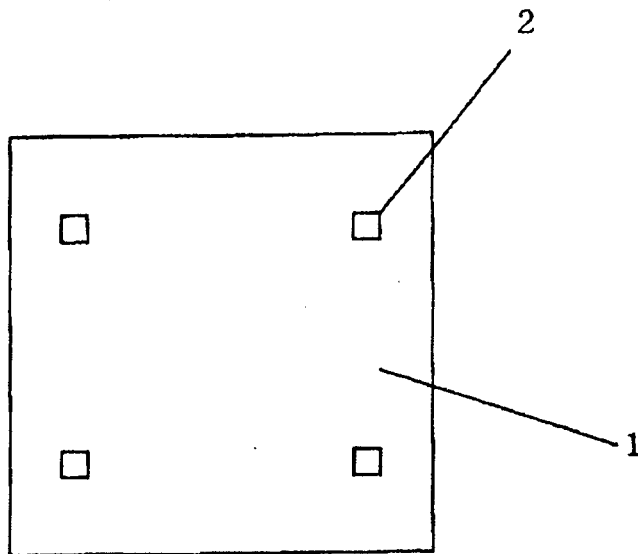
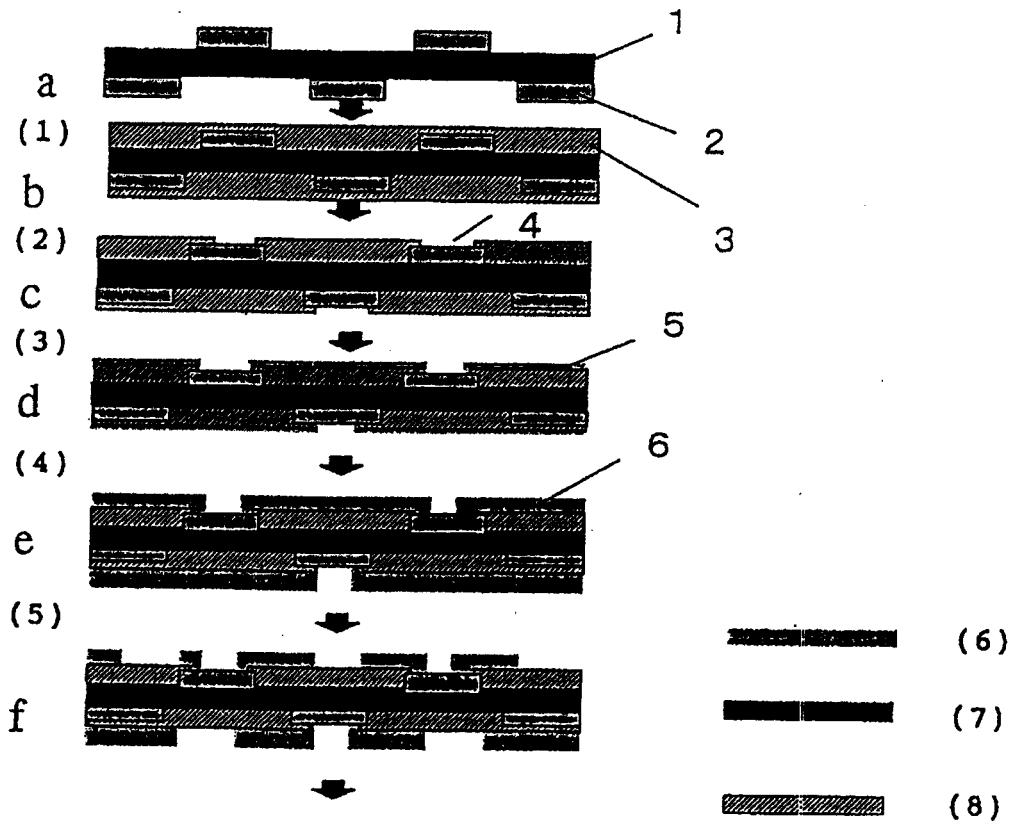


Fig. 2



- (1) Resin layer formation
- (2) Boring
- (3) Electroless copper plating
- (4) Electrolytic copper plating
- (5) Wiring by etching copper
- (6) Copper wiring
- (7) Core substrate
- (8) Insulation resin

Fig. 3

